

# SOT1714-1

plastic, fine-pitch ball grid array; 425 bumps; 0.8 mm pitch; 19 mm x 19 mm x 1.7 mm body

10 January 2019

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	FBGA425
<b>Package type industry code</b>	FBGA425
<b>Package style descriptive code</b>	FBGA (fine-pitch ball grid array)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	07-01-2016
<b>Manufacturer package code</b>	98ASA00148D

**Table 1. Package summary**

<b>Parameter</b>	<b>Min</b>	<b>Nom</b>	<b>Max</b>	<b>Unit</b>
package length	-	19	-	mm
package width	-	19	-	mm
package height	-	1.7	-	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	425	-	



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2 Package outline

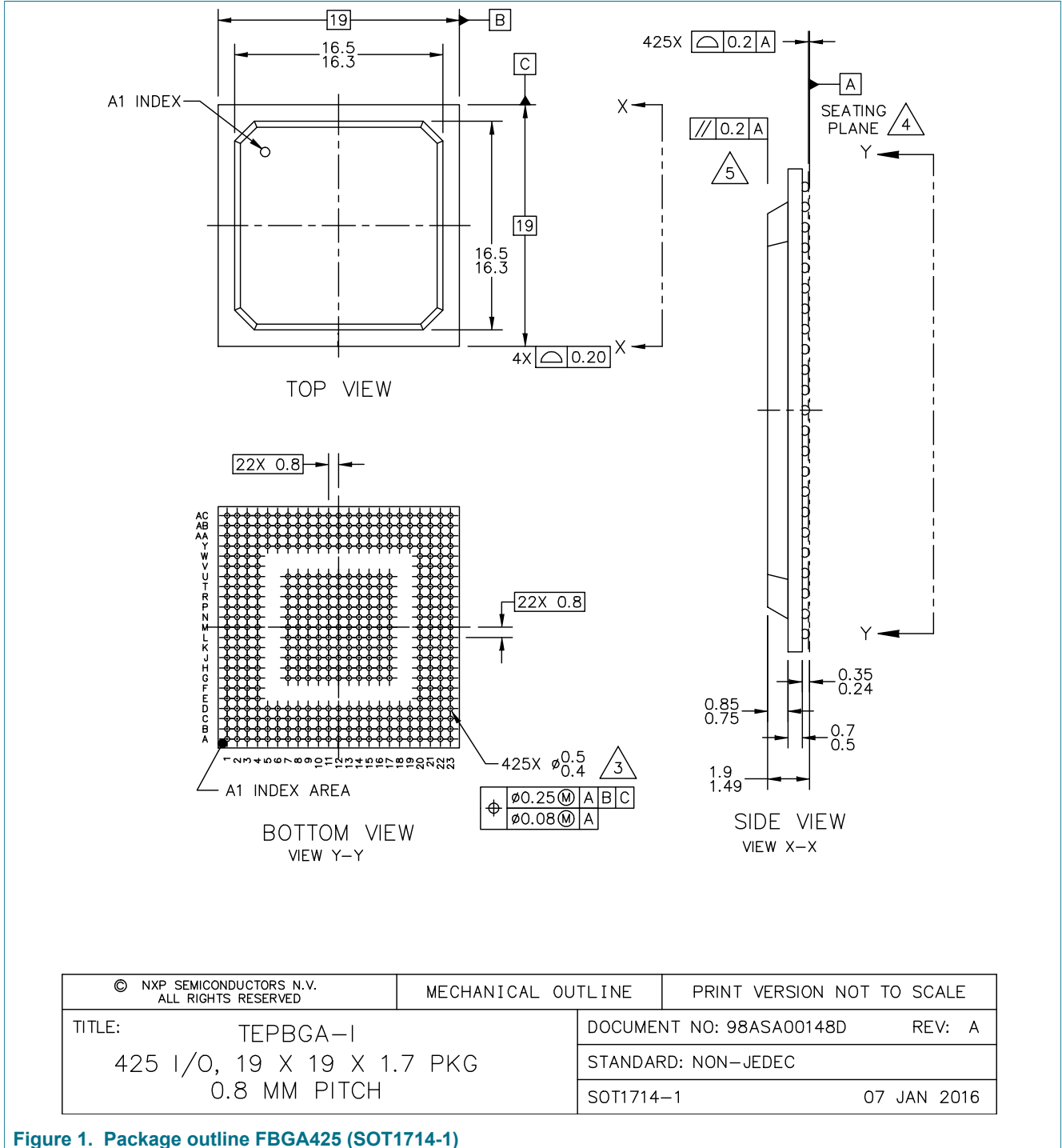


Figure 1. Package outline FBGA425 (SOT1714-1)

plastic, fine-pitch ball grid array; 425 bumps; 0.8 mm pitch; 19 mm x 19 mm x 1.7 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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TITLE: TEPBGA-I 425 I/O, 19 X 19 X 1.7 PKG 0.8 MM PITCH	DOCUMENT NO: 98ASA00148D	REV: A
	STANDARD: NON-JEDEC	
	SOT1714-1	07 JAN 2016

Figure 2. Package outline note FBGA425 (SOT1714-1)

### 3 Legal information

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